

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 14.00L x 11.70W x 1.40H mm
 Weight: Approx. 0.3 g
 Contact principle: Friction technology
 Operating position: Shaft up / Down / Horizontal
 Mounting System: SMT Type (without post)
 Function: Hinge Type
 Durability: 5,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0
 RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

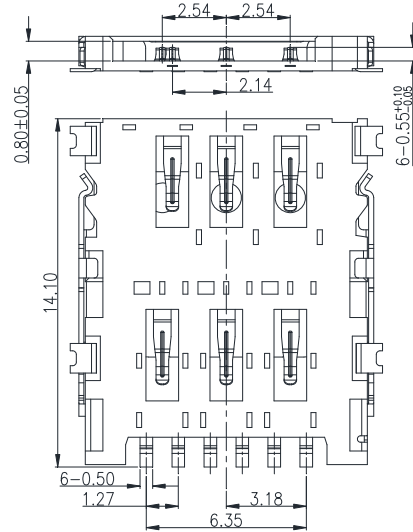
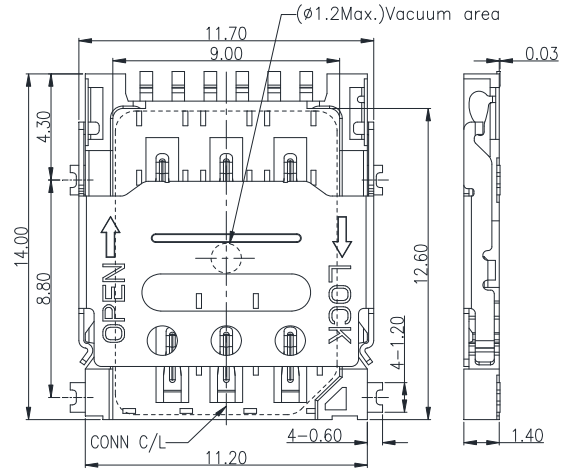
Number of contacts: 6 pins
 Contact resistance: 100 mΩ max.
 Insulation resistance: >1000 MΩ / 500 VDC

4. Solderability

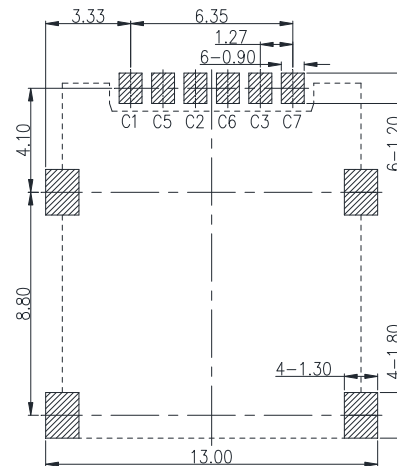
Wave: Not applicable
 IR reflow: 260°C, 10 sec. Max.
 Manual soldering: 360°C, 3 sec. Max.

5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C
 Operating humidity: 10 % ~ 95 % RH
 Storage temperature: - 40°C ~ + 85°C
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm
 Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm
 Reference dimension for PCB layout

HB Nano SIM Card Connector

Model No.: ICC-N01

Revision: 1.2

Date: SEP. 26, 2020

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.

For further information, please contact:

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